

Specifications

Absolute Maximum Ratings at $V_{SS} = 0\text{ V}$

Parameter	Symbol	Conditions	Ratings	Unit
Maximum supply voltage	$V_{DD\text{ max}}$	$T_a = 25^\circ\text{C}$	-0.3 to +7.0	V
Input and output voltages	V_I, V_O	$T_a = 25^\circ\text{C}$	-0.3 to $V_{DD} + 0.3$	V
Allowable power dissipation	$P_d\text{ max}$	$T_a \leq 70^\circ\text{C}$	350	mW
Operating temperature	T_{opr}		-30 to +70	$^\circ\text{C}$
Storage temperature	T_{stg}		-55 to +125	$^\circ\text{C}$
Soldering tolerance (pins only)		10 seconds	260	$^\circ\text{C}$

Allowable Operating Ranges at $T_a = -30\text{ to }+70^\circ\text{C}$, $V_{SS} = 0\text{ V}$

Parameter	Symbol	Conditions	min	typ	max	Unit
Supply voltage	V_{DD}		4.5	5.0	5.5	V
Input voltage range	V_{IN}		0		V_{DD}	V

DC Characteristics: I/O Levels at $T_a = -30\text{ to }+70^\circ\text{C}$, $V_{DD} = 4.5\text{ to }5.5\text{ V}$, $V_{SS} = 0\text{ V}$

Parameter	Symbol	Conditions	min	typ	max	Unit
Input high-level voltage	V_{IH1}	(3), (5)	2.2			V
Input low-level voltage	V_{IL1}	(3), (5)			0.8	V
Input high-level voltage	V_{IH2}	(2), (4)	2.5			V
Input low-level voltage	V_{IL2}	(2), (4)			0.6	V
Input high-level voltage	V_{IH3}	(6), (7)	2.2			V
Input low-level voltage	V_{IL3}	(6), (7)			0.8	V
Input high-level voltage	V_{IH4}	(1)	$0.7 V_{DD}$			V
Input low-level voltage	V_{IL4}	(1)			$0.3 V_{DD}$	V
Output high-level voltage	V_{OH1}	$I_{OH} = -2\text{ mA}$: (4), (5), (6), (9), (10), (11)	$V_{DD} - 2.1$			V
Output low-level voltage	V_{OL1}	$I_{OL} = 2\text{ mA}$: (4), (5), (6), (9), (10), (11)			0.4	V
Output low-level voltage	V_{OL2}	$I_{OL} = 2\text{ mA}$: (7)			0.4	V
Output high-level voltage	V_{OH3}	$I_{OH} = -4\text{ mA}$: (8)	$V_{DD} - 1.5$			V
Output low-level voltage	V_{OL3}	$I_{OL} = 2\text{ mA}$: (8)			0.4	V
Input leakage current	I_{IL}	$V_I = V_{SS}, V_{DD}$: (1), (2), (3), (4), (5)	-10		10	μA
Output leakage current	I_{OZ}	When the output is high impedance: (4), (5), (7), (9)	-10		10	μA
Pull-up resistance	R_{UP}	(6), (7)	40	80	160	$\text{k}\Omega$

Note: The numbers in parentheses in the table refer to the following applicable output pin sets:

Input

(1)XTALCK

(2)BICKIN, BITDATAI, ROUGH, SBSO, SCOR, WFCK, $\overline{\text{CMD}}$, $\overline{\text{CS}}$, ENABLE, $\overline{\text{HRD}}$, $\overline{\text{HWR}}$, RD, RESET, WR

(3)BCK, C2PO, CPUCNT, HDTATT, LOCKIN, LRCK, RS, SDATA, SELDRQ, SUA0 to SUA6, EXTSYNC, HDREN, TEST, TEST5, TEST6

In/Out

(4)PLLOUTIN

(5)ATIPSYNC, SVSWITCH

(6)D0 to D7, HD0 to HD7, IO0 to IO7, MD0 to MD7

Output

(7)INT

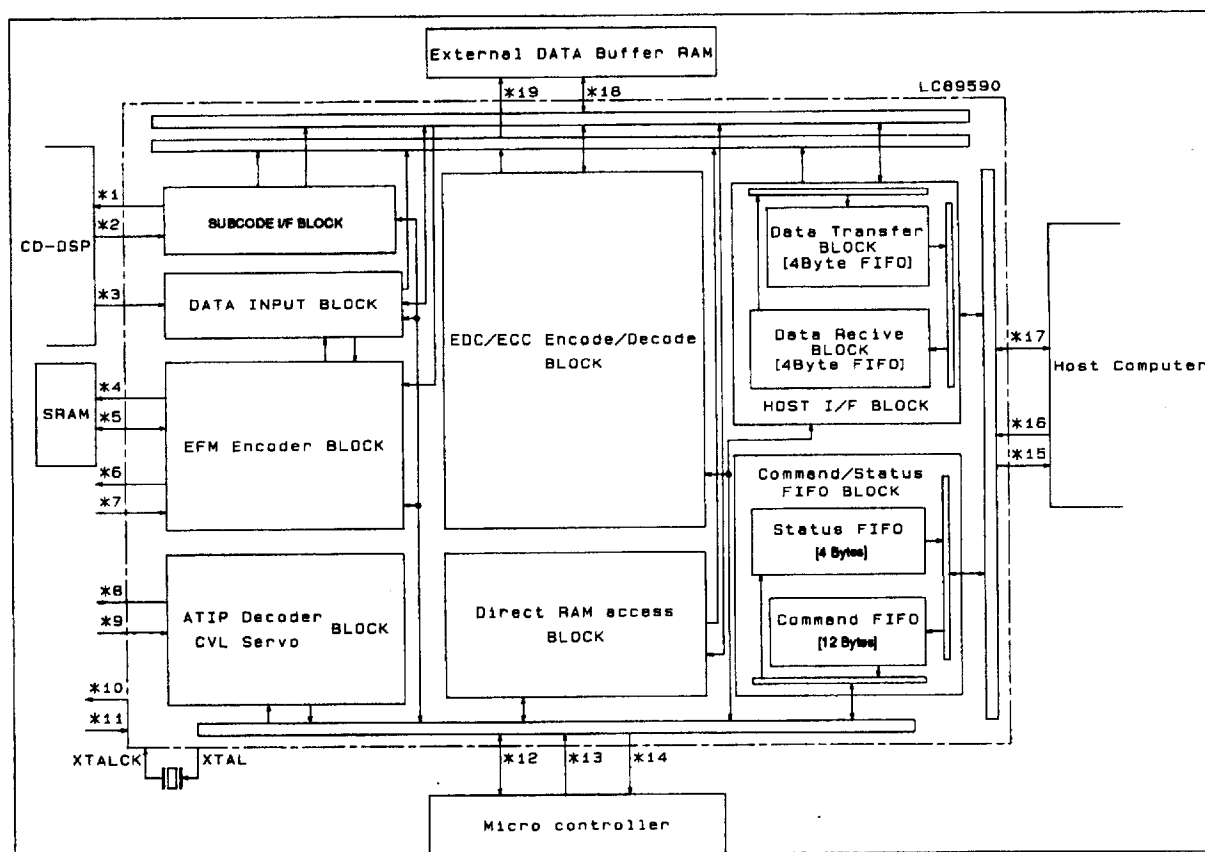
(8)XTAL

(9)CLV + (MDP), CLV - (MDS)

(10)EXCK, DREN, DTEN, EOP, RCS, ROE, RWE, STEN, WAIT

(11)RAS, CAS, DATA0, DATALR0, DATA1, DATAW0, DATSPCA, EFM, EFMG, EFMS, FRCK, LOCK, OSDATA, PSUBSYNC, SUBSYNC, TTT, ERROR, EXTACK, SWAIT, LINKPOS0, MAD0 to MAD11, MRD, MWR, RA0 to RA10

Block Diagram



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Note: 1. EXCK

- 2. WFCK, SBSO, SCOR
- 3. BCK, SDATA, LRCK, C2PO
- 4. MAD0 to MAD11, MRD, MWR
- 5. MD0 to MD7
- 6. SUBSYNC, PSUBSYNC, FRCK, DATAST, DATSPCA, EFM, EFMG, EFMS, LINKPOS, TTT, EXTACK, OSDATA
- 7. EXTSYNC, ATIPSYNC
- 8. ERROR, ATIPSYNC, LOCK, CLV + (MDP), CLV - (MDS)
- 9. PLLOUTIN, ROUGH, SVSWITCH, LOCKIN, BICKIN, BIDATAIN
- 10. TEST1 to TEST4 (Not connect)
- 11. TEST5, TEST6 (GND), RESET
- 12. D0 to D7
- 13. CS, RS, RD, WR, CPUCNT, SUA0 to SUA6, SELDRQ
- 14. SWAIT, INT
- 15. DREN, DTEN, STEN, EOP, WAIT/DRQ
- 16. ENABLE, CMD, HRD, HWR, DTATT, HDREN
- 17. HD0 to HD7
- 18. IO0 to IO7
- 19. RA0 to RA10, RAS, CAS, ROE, RWE, RCS

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Pin Functions

Type: I: Input pin, O: Output pin, B: Bidirectional pin, P: Power supply pin, NC: No connection pin

Pin No.	Symbol	I/O	Description
1	V _{SS}	P	
2	TEST1	NC	Test inputs Leave pins 2 to 5 open. Pins 6 and 7 must be tied low.
3	TEST2	NC	
4	TEST3	NC	
5	TEST4	NC	
6	TEST5	I	
7	TEST6	I	
8	ROE	O	Read, write, and select lines for the ROM encoder and decoder buffer RAM.
9	RWE	O	
10	RCS	O	
11	V _{DD}	P	
12	IO0	B	Data signal lines for the ROM encoder and decoder buffer RAM. Pull-up resistors are built in.
13	IO1	B	
14	IO2	B	
15	IO3	B	
16	IO4	B	
17	IO5	B	
18	IO6	B	
19	IO7	B	
20	V _{DD}	P	
21	V _{SS}	P	
22	RAS	O	DRAM RAS signal output
23	V _{SS}	P	
24	CAS	O	DRAM CAS signal output
25	V _{DD}	P	
26	RA0	O	Address signal outputs to the ROM encoder and decoder buffer RAM.
27	RA1	O	
28	RA2	O	
29	RA3	O	
30	RA4	O	
31	RA5	O	
32	TEST	I	Test input. Must be tied low.
33	RA6	O	Address signal outputs to the ROM encoder and decoder buffer RAM.
34	RA7	O	
35	RA8	O	
36	RA9	O	
37	RA10	O	
38	RESET	I	Chip reset input
39	SUA0	I	Command register selection address
40	V _{DD}	P	
41	V _{SS}	P	
42	SUA1	I	Command register selection address
43	SUA2	I	
44	SUA3	I	
45	SUA4	I	
46	SUA5	I	
47	SUA6	I	
48	V _{SS}	P	

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Type: I: Input pin, O: Output pin, B: Bidirectional pin, P: Power supply pin, NC: No connection pin

Pin No.	Symbol	I/O	Description
49	D0	B	Microprocessor data signal lines Pull-up resistors are built in.
50	D1	B	
51	D2	B	
52	D3	B	
53	D4	B	
54	D5	B	
55	D6	B	
56	D7	B	
57	$\overline{\text{SELD}}\overline{\text{DRQ}}$	I	Mode selection for transfers to the host (WAIT control, DRQ control)
58	$\overline{\text{RD}}$	I	Microprocessor data read signal input
59	$\overline{\text{WR}}$	I	Microprocessor data write signal input
60	V _{DD}	P	
61	V _{SS}	P	
62	$\overline{\text{CS}}$	I	Chip select signal input from the microprocessor
63	RS	I	Register select signal
64	$\overline{\text{SWAIT}}$	O	Sub-CPU wait signal
65	$\overline{\text{INT}}$	O	Interrupt request signal output to the microprocessor
66	$\overline{\text{ENABLE}}$	I	Chip select signal input from the host
67	$\overline{\text{CMD}}$	I	Command/data selection signal input from the host
68	$\overline{\text{HWR}}$	I	Host data write signal input
69	$\overline{\text{HRD}}$	I	Host data read signal input
70	CPUCNT	I	Indirect/direct addressing selection signal input
71	HD0	B	Host data signals Pull-up resistors are built in.
72	HD1	B	
73	HD2	B	
74	HD3	B	
75	HD4	B	
76	HD5	B	
77	HD6	B	
78	HD7	B	
79	$\overline{\text{WAIT}}$	O	Wait signal output to the host. Can be switched to output the DRQ signal.
80	V _{DD}	P	
81	V _{SS}	P	
82	DTEN	O	Data enable signal output
83	$\overline{\text{STEN}}$	O	Status enable signal output
84	EOP	O	End of process signal output. Used during DMA data transfers.
85	DREN	O	Data receive enable signal output
86	DTATT	I	ROM data/subcode data switching input
87	HDREN	I	Transfer enable signal input from host
88	EXCK	O	Subcode I/O
89	WFCK	I	
90	SBSO	I	
91	SCOR	I	
92	V _{DD}	P	
93	ERROR	O	ATIP parity error detection output
94	LOCK	O	CLV servo lock monitor
95	LOCKIN	I	CD decoder lock signal input
96	BICKIN	I	Biphase data transfer clock input
97	BIDATAI	I	Biphase data input
98	CLV + (MDP)	O	CLV servo signal output
99	CLV - (MDS)	O	CLV servo signal output
100	V _{DD}	P	
101	V _{SS}	P	
102	PLLOUTIN	B	Wobble signal carrier wave clock input

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Type: I: Input pin, O: Output pin, B: Bidirectional pin, P: Power supply pin, NC: No connection pin

Pin No.	Symbol	I/O	Description
103	ROUGH	I	Wobble signal input for rough CLV servo
104	SVSWITCH	B	CLV servo reference clock selection input
105	SDATA	I	Serial data input
106	BCK	I	Serial data input clock
107	LRCK	I	44.1 kHz strobe signal input
108	C2PO	I	C2 pointer input
109	V _{SS}	P	
110	XTALCK	I	Crystal oscillator circuit input (17.2872 MHz)
111	XTAL	O	Crystal oscillator circuit output
112	V _{SS}	P	
113	V _{SS}	P	
114	MWR	O	EFM encoder SRAM write signal
115	MRD	O	EFM encoder SRAM read signal
116	MAD0	O	EFM encoder SRAM address signal outputs
117	MAD1	O	
118	MAD2	O	
119	MAD3	O	
120	V _{DD}	P	
121	V _{SS}	P	
122	MAD4	O	EFM encoder SRAM address signal outputs
123	MAD5	O	
124	MAD6	O	
125	MAD7	O	
126	MAD8	O	
127	V _{DD}	P	
128	MAD9	O	EFM encoder SRAM address signal outputs
129	MAD10	O	
130	MAD11	O	
131	MD0	B	EFM encoder SRAM data signals
132	MD1	B	
133	MD2	B	
134	V _{SS}	P	
135	MD3	B	EFM encoder SRAM data signals
136	MD4	B	
137	MD5	B	
138	MD6	B	
139	MD7	B	
140	V _{DD}	P	
141	V _{SS}	P	
142	EXTSYNC	I	ATIP synchronization enable signal input
143	EXTACK	O	ATIP synchronization acknowledge signal output
144	ATIPSYNC	B	ATIP synchronization signal I/O
145	PSUBSYNC	O	Pseudo-subcode synchronization output
146	EFMG	O	EFM output gate signal
147	LINKPOS	O	Link position signal output
148	EFMS	O	Outputs the logical AND of the EFM and EFMG signals.
149	EFM	O	EFM signal output
150	TTT	O	3T detection signal output

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Type: I: Input pin, O: Output pin, B: Bidirectional pin, P: Power supply pin, NC: No connection pin

Pin No.	Symbol	I/O	Description
151	V _{SS}	P	
152	DATAACKO	O	4.3218 MHz oscillator output
153	DATALRCO	O	44.1 kHz oscillator output
154	DATAWDCO	O	88.2 kHz oscillator output
155	OSDATA	O	ROM encoded data serial output
156	FRCK	O	EFM frame synchronizing signal output
157	DATAST	O	Data start monitor signal output
158	DATSPCA	O	Data/PCA monitor signal output
159	SUBSYNC	O	Subcode synchronizing signal output
160	V _{DD}	P	

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